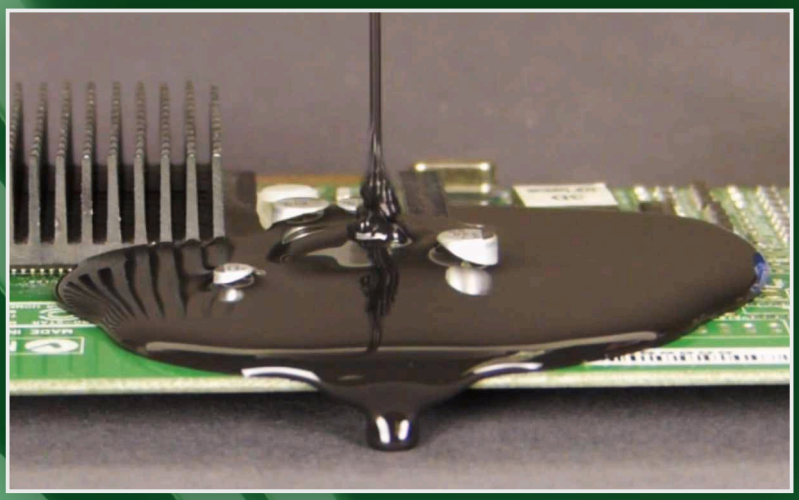


SE2011

Self Bonding Silicone Encapsulant for Electronics

SE2011 is a self-bonding condensation cure, black, 23 Shore 'A' potting compound. Unlike addition cure encapsulants, SE2011 will develop chemical adhesion after 24 hours at room temperature without the need for heat or the application of a primer. Its self-generated adhesion ensures a watertight seal that will provide maximum protection for delicate electronics.



Key characteristics:

- Self-Bonding
- Easy 10:1 mix ratio by weight
- Very flowable with a mixed viscosity of 4000 mPas
- Excellent adhesion develops at room temperature - NO heat required
- UL94 HB certified
- Hardness 23 Shore A
- Pot life 20 min
- Black

Properties Before Cure	
Ratio A:B by weight/volume	10:1
Appearance A part	Black Liquid
Appearance B part	Clear Liquid
Mixed viscosity	4000 mPa-s
SG A Part	1.10
SG B Part	0.96
Pot life at 23°C	20 mins
Cure time to handle	2 hours

Cured Elastomer (After 7 days cure at 23+/- 2°C and 45 to 55% humidity)	
Hardness	23 Shore A
Tensile Strength	0.90Mpa
Elongation	270%
Youngs Modulus	0.23Mpa
CTE, Linear	279ppm/°C
CTE, Volumetric	837ppm/°C
Flame Rating	UL94-HB

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